NEWS BULLETIN

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For immediate release

Unitive Electronics Qualifies in Production NEXX Systems' Stratus Electro-deposition System

Billerica, MA – July 12, 2004 – NEXX Systems today announced the acceptance of its Stratus 100 electro-deposition system at the Unitive Electronics, Inc. plant in Research Triangle Park, NC. Unitive will use NEXX's electroplating system for development of its lead-free and tin-lead based alloys.

"Using the Stratus from NEXX Systems adds to Unitive's lead in wafer electroplating. NEXX's unique contact and seal technology reliably unlocks the cost and performance advantages of vertical fluid-agitated deposition," explained J. Daniel Mis, vice president of technology integration at Unitive. "The NEXX Systems' tool, having been designed specifically for thick film plating processes for advanced packaging, also provides ease of use and maintenance features important to Unitive as we climb an aggressive volume ramp."

"We are very pleased to have won Unitive's business. The acceptance and shipment of this system represents a key milestone in the introduction of this breakthrough technology in electro-deposition," said Arthur Keigler, vice president of technology at NEXX Systems. "We recognize Unitive as a leader in advanced packaging and believe this installation represents the continuation of a very fruitful relationship for both companies."

New technology from NEXX Systems -- the Shear-Plate™ processing module -- provides a revolutionary thin, constant, and uniform fluid boundary layer at the wafer surface. Stratus provides the highest possible deposition rates, two or more times faster than fountain cell technology, with improved deposition uniformity. A patented wafer-holding module that simultaneously creates a robust fluid seal and uniform electrical contact to the wafer ensures leak free operation and eliminates contact and seal maintenance problems.

Unitive is a leading provider of turnkey wafer-level packaging solutions that make semiconductors smaller, faster, and lighter. The company partners with its customers to meet their product and global manufacturing needs through innovative deployment of its technologies. Unitive's services include multi-level passivation and thin film wiring, solder bumping, and chip scale packaging. Additional information can be found at: *www.unitive.com*. At Semicon West 2004. please visit Booth #12170, McEnery Convention Center, San Jose.

NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional

information can be found at: *www.nexxsystems.com.* At Semicon West 2004. please visit Booth #5226, North Hall, Moscone Center, San Francisco.

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